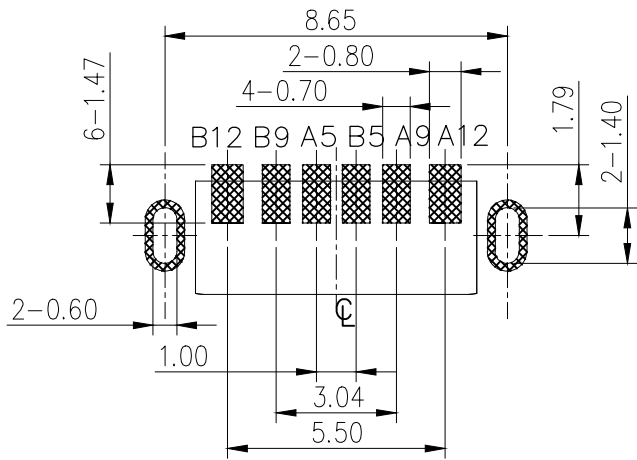
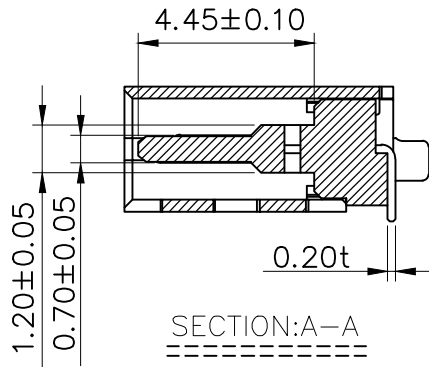
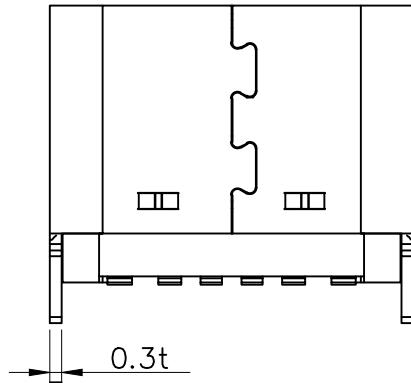
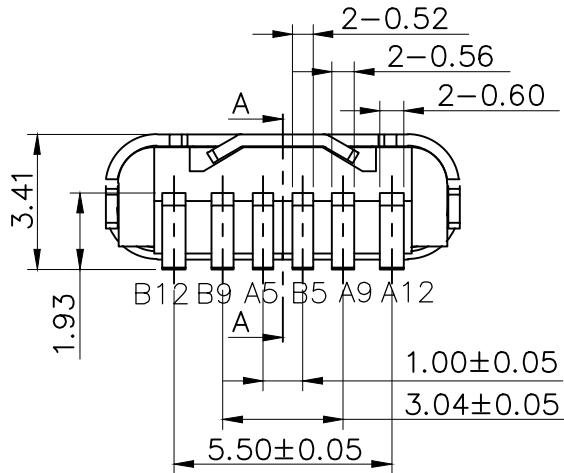
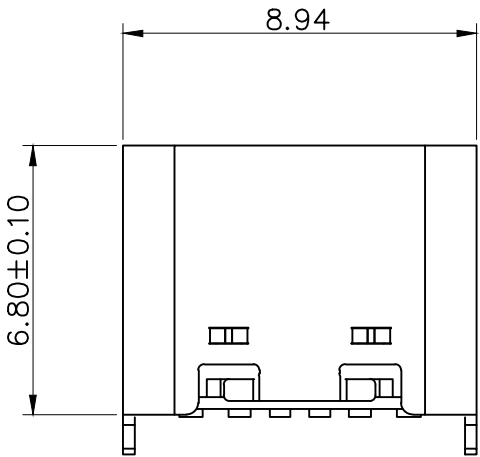
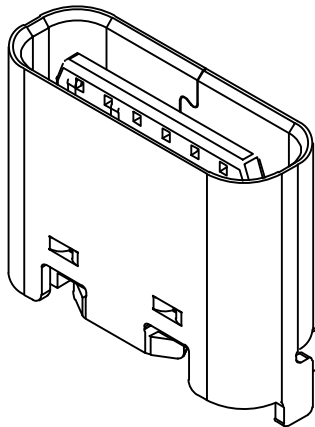
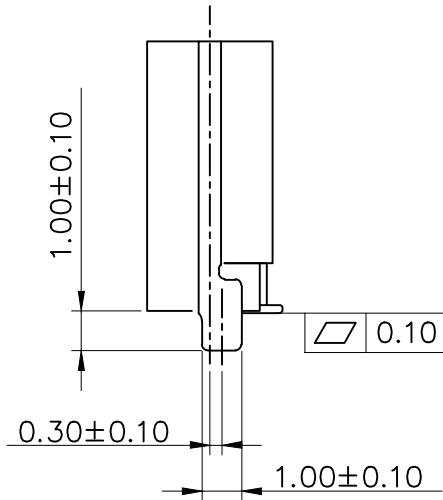
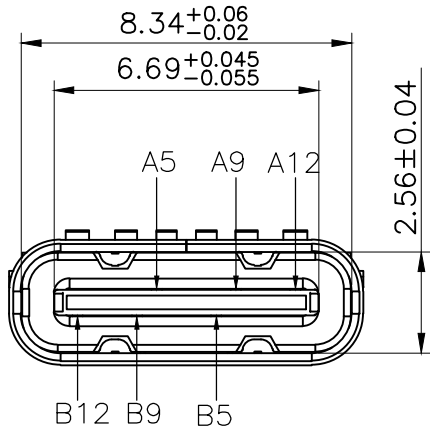


标 记 MARK	ECN编号/变更内容 ECN NO/DEFINITION		修 改 REVISE	日 期 DATE	核 准 APPROVE
PIN NUMBER		SIGNAL NAME	PIN NUMBER		SIGNAL NAME
A12		GND	B12		GND
A9		VBUS	B9		VBUS
A5		CC1	B5		CC2



RECOMMENDED PCB LAYOUT(TOP VIEW)
THICKNESS 0.80MM;DEFAULT TOLERANCE:±0.05

NOTE1:
1.MATERIAL SPECIFICATION:
1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC.
2.CONTACTS:COPPER ALLOY
3.MID PLATE: STAINLESS STEEL
4.FRONT SHELL: STAINLESS STEEL 201 T3.0
2.PLATING SPECIFICATION:
2-1.CONTACTS:
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
2-2.FRONT SHELL:
Ni 30u" MIN. UNDER PLATED OVER ALL.
2-3.SHIELD PLATE&EMI PLATE:
CLEAR ONLY
3.MECHANICAL PERFORMANCE,
3-1.INSERTION FORCE: 0.5~2.0kgf.
3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
3-3.DURABILITY: 3000 CYCLES.
4.ELECTRICAL PERFORMANCE,
4-1. CURRENT RATING:3.0A
VOLTAGE RATING:5.0V
4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
SHIELD: 50mΩ/MAX.
LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
4-3.INSULATION RESISTANCE: 100MΩ MIN
4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -25°C~+85°C.
6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260°C.

3	外壳	不锈钢	镀镍	
2	接触	铜	镀金	
1	基座	LCP	黑色	
序 号	品 名	材 质	电镀/颜色	备 注



深圳市虹成电子有限公司

品 名 TITLE	TYPE-C母座		
料 号 PART NO	HC-TYPE-C-6P-LT023A		

GENERAL TOLERANCES (UNLESS SPECIFIED)		比 列 SCALE	1:1	制 图 DRAW		审 核 CHECKED		批 准 APPROVE	
X	±0.25	X°	±3°	单 位 UNIT	MM	制 图 DRAW	AhYe		
.X	±0.20	.X°	±2°	张 数 PART NO	1 OF 1	审 核 CHECKED	夏操云		
.XX	±0.15	.XX°	±1°	版 本 REV	A	批 准 APPROVE	赵亮亮		
.XXX	±0.08								